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23494 7590 06/09/2004

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<b>Karen Vertz</b>	(Depositor's name)
<i>Karen Vertz</i>	(Signature)
6-16-04	(Date)

APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/608,921	06/27/2003	Jiong-Ping Lu	TI-35330	7024

**TITLE OF INVENTION:** COPPER SURFACE PASSIVATION DURING SEMICONDUCTOR MANUFACTURING

APPLN. TYPE	SMALL ENTITY	ISSUE FEE	PUBLICATION FEE	TOTAL FEE(S) DUE	DATE DUE
nonprovisional	NO	\$1330	\$300	\$1630	09/09/2004

EXAMINER	ART UNIT	CLASS-SUBCLASS
GURLEY, LYNNE ANN	2812	438-626000

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1 **Rose Alyssa Keagy**  
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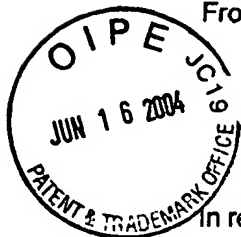
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## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Applicant Jiong-Ping Lu, et al.

Docket Number: TI-35330

Serial No.: 10/608,921

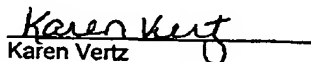
Art Unit: 2812

Filed: 06/27/03

Examiner: Lynne Ann Gurley

For: Copper Surface Passivation During Semiconductor  
Manufacturing

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NAME OF INVENTOR(S): Jiong-Ping Lu	
TITLE OF INVENTION: Copper Surface Passivation During Semiconductor Manufacturing	
TI FILE NO.: TI-35330	DEPOSIT ACCT. NO.: 20-0668
FAXED: 6-16-04 DUE: 9-9-04 ATTY/SECY: RAK/kjv	
RECEIPT DATE & SERIAL NO.: Serial No.: 10/608,921 Filing Date: 06/27/03	

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